

**Notice of References Cited**

Application/Control No.

09/916,491

Applicant(s)/Patent Under

Reexamination

GERRITS ET AL.

Examiner

D. I. Lee

Art Unit

2876

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**U.S. PATENT DOCUMENTS**

| * |   | Document Number<br>Country Code-Number-Kind Code | Date<br>MM-YYYY | Name             | Classification |
|---|---|--|-----------------|------------------|----------------|
|   | A | US-5,736,646 A1                                  | 04-1998         | Dickinson et al. | 73/814         |
|   | B | US-  |                 |                  |                |
|   | C | US-  |                 |                  |                |
|   | D | US-  |                 |                  |                |
|   | E | US-  |                 |                  |                |
|   | F | US-  |                 |                  |                |
|   | G | US-  |                 |                  |                |
|   | H | US-  |                 |                  |                |
|   | I | US-  |                 |                  |                |
|   | J | US-  |                 |                  |                |
|   | K | US-  |                 |                  |                |
|   | L | US-  |                 |                  |                |
|   | M | US-  |                 |                  |                |

**FOREIGN PATENT DOCUMENTS**

| * |   | Document Number<br>Country Code-Number-Kind Code | Date<br>MM-YYYY | Country | Name | Classification |
|---|---|--|-----------------|---------|------|----------------|
|   | N |  |                 |         |      |                |
|   | O |  |                 |         |      |                |
|   | P |  |                 |         |      |                |
|   | Q |  |                 |         |      |                |
|   | R |  |                 |         |      |                |
|   | S |  |                 |         |      |                |
|   | T |  |                 |         |      |                |

**NON-PATENT DOCUMENTS**

| * |   | Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)  |
|---|---|--|
|   | U | Keizou Sakurai, Electronic Manufacturing Technology Symposium, 1995, [The basic processing parameters and reliability evaluation results for the new IC-Card packaging method by using transfer molding] |
|   | V | Ed Marsh, IEEE Technical Applications Conference and Workshops Northcon95, Oct. 1995 [Packaging Guidelines for PC Cards]   |
|   | W |  |
|   | X |  |

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.